

## **IMPACT 2015 online registration is open now!!!**

**★Wearable★IoT★Market & Technical Trends ★ Cutting-edge Technologies**

**Get Early bird discount before Oct. 3**

**[<<Online Register Here>>](#)**

International Microsystems, Packaging, Assembly and Circuits Technology Conference—IMPACT 2015 is going to call for attendees from now. You can get early bird discount from now to Oct. 3!

The IMPACT Conference is the largest gathering of packaging and PCB professionals in Taiwan, attracting over 4,000 attendees in accumulated total over the past years. To reflect the cutting-edge technology development, the IMPACT Conference highlights “IMPACT on Mobile and Flexible Electronics”. The IMPACT 2015 conference, which will be held in conjunction with TPCA Show and The 6th ICFPE (International Conference on Flexible and Printed Electronics) at Taipei Nangang Exhibition Center on October 21 - 23, 2015, is celebrating its 10th anniversary of bringing worldwide leading experts and engineers together in sharing state-of-the-art advanced microelectronic packaging and PCB technology.

IMPACT is honored to present famous **plenary speakers** including **E. Jan Vardaman** (President of TechSearch) who will share “Packaging Trends for Wearable Medical Electronics”. In the meanwhile, **Dr. Yasumitsu Orii** (Senior Manager of IBM Japan, Ltd.) will give a speech titled “Challenge of Packaging Technologies in the era of Cognitive Computing”. Moreover, we will have variety of industrial theme sessions including **SPIL's** “2.5D IC, SiP, Fan-out, and NTI (No TSV Interposer)”、**Intel's** “Intel Data Center Design Strategy” and **ASE**.

Meanwhile, you can find **6 special sessions** this year! **Wearable Session**、**IoT Session**、**ICEP Japan Session**、**iNEMI Session**、**Korea Session** and **TPCA-PCB Thesis Award Session**. In addition, we are honored to have Prof. Tadatomo Susa to share “Surface Activated Bonding - A low temperature bonding process for next generation interconnect technology” and Dr. Charles E. Bauer to share “Emerging Packaging Trends”. Otherwise, IMPACT is highly delighted to have the support from industrial field such as AEM, ASE, Atotech, BoardTek, Dow, Eternal, Intel, JSR, SPIL and etc. Sponsorship program is continually open.

2015, the most representative conference all over the world, successfully attracted more than **200 papers** from industries, academics and research organizations which come from **16 areas** such as, Australia, China, France, Germany, Hong Kong, India, Israel, Japan, Malaysia, Netherlands, Philippines, Singapore, South Korea, Thailand, U.S.A and Taiwan etc. If you are eager to master the latest technology trends, you must not miss the IMPACT 2015 International conference! Moreover, IMPACT provides special service-**Plant tour!!** And it's **only for overseas and students**. You can visit Taiflex Company with cultural tour. Limited quantities and go to register right now! Please visit the official website (<http://www.impact.org.tw>) or contact the secretariat (Tel: 886-3-3815659 #407). **You can get early bird discount before October 3.**

### **【Conference Program】**

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